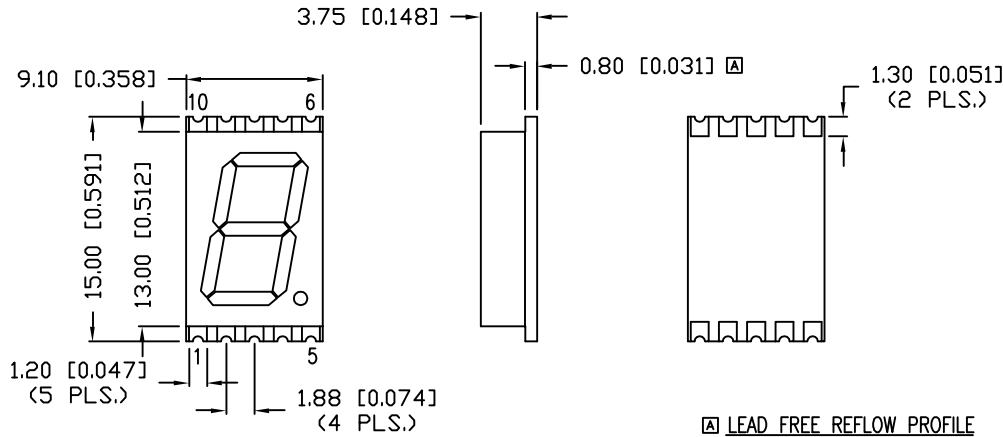


UNCONTROLLED DOCUMENT

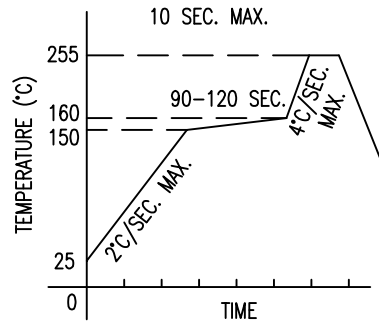
PART NUMBER		REV.
LDS-SMA4002RIUPGTR		A
REV.	E.C.N. NUMBER AND REVISION COMMENTS	DATE
A	E.C.N. #11446.	9.27.07



ELECTRO-OPTICAL CHARACTERISTICS  $T_A=25^{\circ}\text{C}$   $I_f=10\text{mA}$

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		525		nm	
FORWARD VOLTAGE		3.5	4.0	$V_f$	
REVERSE VOLTAGE	5.0			$V_r$	$I_r=100\mu\text{A}$
AXIAL INTENSITY		7000		$\mu\text{cd}$	$I_f=10\text{mA}$
EMITTED COLOR:	GREEN				
FACE COLOR:	GRAY				
SEGMENT COLOR:	MILKY WHITE DIFFUSED				

LEAD FREE REFLOW PROFILE

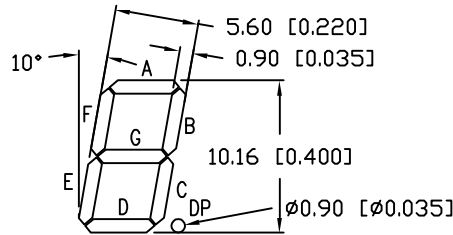


LIMITS OF SAFE OPERATION AT 25°C PER CHIP

PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	150	mA
STEADY CURRENT	25	mA
POWER DISSIPATION	105	mW
DERATE FROM 25°C	-1.2	mW/°C
OPERATING, STORAGE TEMP.	-40 TO +85	°C

\*  $t < 10\mu\text{s}$

DIGIT DETAIL

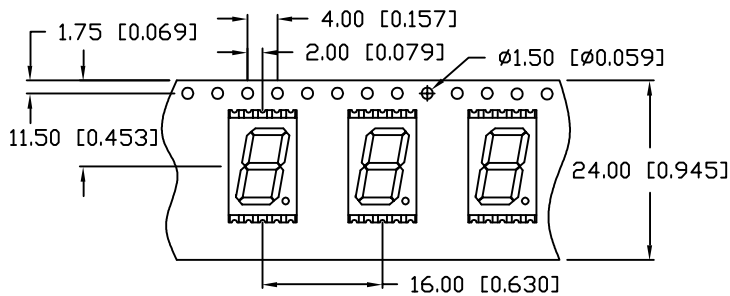
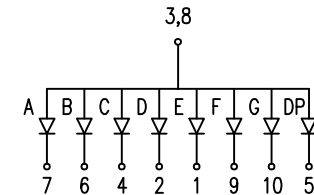


TOTAL TIME ABOVE 220°C IS 60 SECONDS MAX.

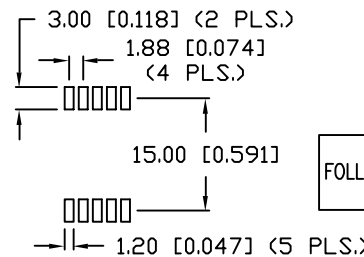
NOTES:

1. 800 PCS/REEL

POLARITY DIAGRAM



SOLDER PAD LAYOUT



CAUTION: STATIC SENSITIVE DEVICE  
FOLLOW PROPER E.S.D. HANDLING PROCEDURES  
WHEN WORKING WITH THIS PART.

TAPE FEED DIRECTION →

\*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), X.X=±0.5 (±0.020), X.XX=±0.25 (±0.010), X.XXX=±0.127 (±0.005). LEAD SIZE=±0.05 (±0.002), LEAD LENGTH=±0.75 (±0.030). MIN.= +DECIMAL PRECISION -0.00, MAX.= +0.00 -DECIMAL PRECISION

UNCONTROLLED DOCUMENT

REV.	PART NUMBER
A	LDS-SMA4002RIUPGTR

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0.40" 7 SEGMENT DISPLAY, GRAY FACE,  
525nm GREEN CHIPS, WHITE SEGMENTS, COMMON ANODE.

**RELIABILITY NOTE**  
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY:	CHECKED BY:	APPROVED BY:	DATE:
GB			8.26.03
			PAGE: 1 OF 1
			SCALE: N/A